



GAU 2815
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.:
NSC1P217D2/NS-3877-2

Application No.: 09/625,071

Examiner: Clark, S.

Filed: July 25, 2000

Group: 2815

Title: LEAD FRAME CHIP SCALE PACKAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Assistant Commissioner for Patents, Washington, DC 20231 on September 7, 2001.

Signed: Lara M. Nelson
Lara M. Nelson

COMMUNICATION

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Enclosed herewith is a Power of Attorney by Assignee and Revocation of Previous Powers for the above-identified patent application. Please enter this document in the file.

Should the Examiner have any questions concerning this matter, the undersigned can be reached at the telephone number set out below.

Respectfully submitted,

BEYER WEAVER & THOMAS, LLP

Steve D Beyer
Steve D Beyer
Reg. No. 31,234

P.O. Box 778
Berkeley, CA 94704-0778

RECEIVED
SEP 14 2001
TECHNOLOGY CENTER 2000